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DIALOG(R)File 351:Derwent WPI

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Cosmetic material for skin conditioning - contains organic silicone resin

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Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 62298518	A	19871225	JP 86143758	A	19860619	198806 B

Priority Applications (No Type Date): JP 86143758 A 19860619

Patent Details:

Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
JP 62298518	A		3		

Abstract (Basic): JP 62298518 A

Material contains 1-70 wt.% organic silicone resin, 70 mol% or more of which comprises R₃SiO_{1/2} unit (R = hydrocarbon gp. or phenyl gp. of 1-6C) and SiO₂ unit of mol ratio 0.5/1-1.5/1.

USE/ADVANTAGE - The material effectively protects skin (esp. hands) from roughness caused by work using water, for long time. It is smoothly applied, and not washed away easily by washing with water.

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Title Terms: COSMETIC; MATERIAL; SKIN; CONDITION; CONTAIN; ORGANIC; SILICONE; RESIN

Derwent Class: A26; A96; D21

International Patent Class (Additional): A61K-007/48

File Segment: CPI